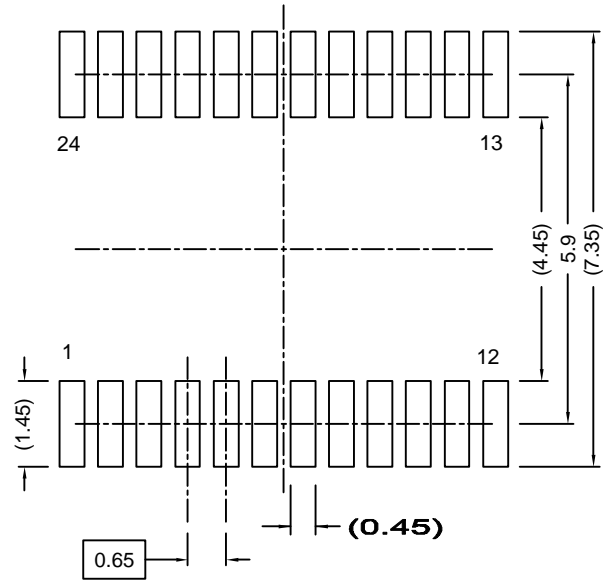
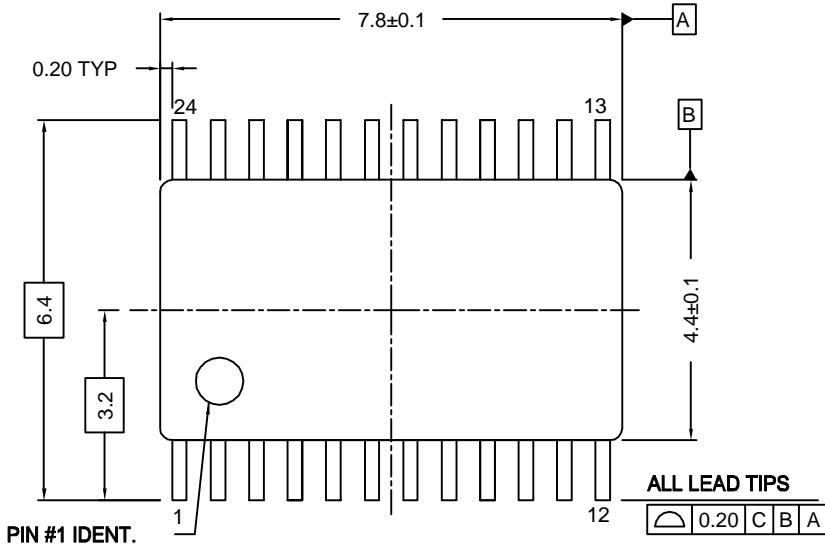
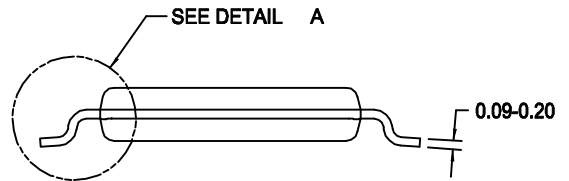
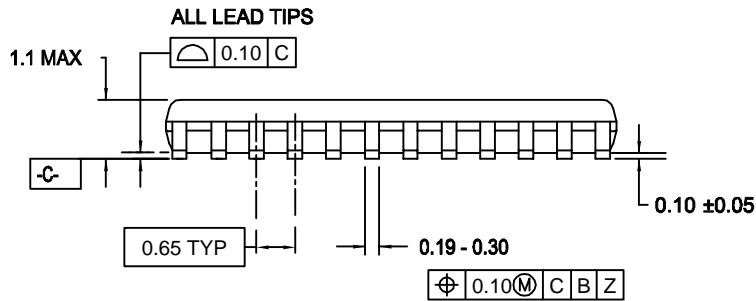


**REVISIONS**

LTR	DESCRIPTION	EDCN	DATE	BY/APPD
4	CHANGE TO FSPM DRAWING FORMAT N LEAD SHIFT TOL. FROM 0.13MM TO 0.10MM	ECN-MTC24REV4	21/12/2006	H.ALLEN



**LAND PATTERN RECOMMENDATION**  
REFERENCE: TSOP65P640X110-24N

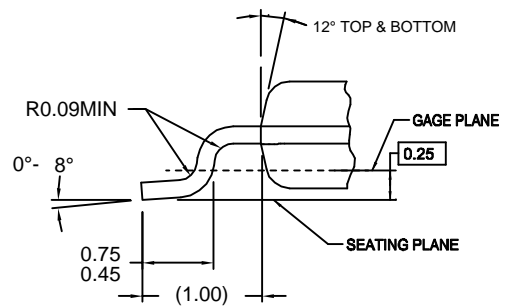


DIMENSIONS ARE IN MILLIMETERS

**NOTES:**

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AD, DATE 10/97.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1994
- E. DRAWING FILE NAME: MTC24REV4

MTC24REV4



DETAIL A

APPROVALS	DATE	FAIRCHILD SEMICONDUCTOR™			
DRAWN: FEITAN	8-10-99	Bayan Lepas, FIZ, 11900, Penang, Malaysia.			
DFTG. CHK: H.ALLEN	21-12-2006	24LD, TSSOP, JEDEC MO-153, 4.4MM WIDE			
ENGR. CHK:					
		SCALE: N/A	SIZE: A4	DRAWING NUMBER: MKT-MTC24	REV: 4
		DO NOT SCALE DRAWING		SHEET 1 of 1	